



## 2026 IEEE EMC SOCIETY STUDENT HARDWARE DESIGN COMPETITION

**“Characterize the EMC of a Working Gadget”**

*Inspire - Measure - Mitigate*

The IEEE Electromagnetic Compatibility (EMC) Society  
invites student teams to participate in the

**2026 STUDENT HARDWARE DESIGN COMPETITION,**  
focused on developing practical skills in EMC measurement, analysis,  
and problem solving. This year’s challenge asks students to characterize  
the electromagnetic compatibility (EMC) performance of a working  
electronic device — an Arduino-based system and to communicate  
results clearly and creatively.

The competition emphasizes real-world engineering practice:  
designing test setups, collecting meaningful data, interpreting results,  
and proposing or demonstrating mitigation techniques.

### TECHNICAL CHALLENGE

#### Teams will:

1. Purchase a [L298N Motor Drive Controller Board Stepper Motor Control Module Dual H-Bridge with DC Motor and Smart Car Wheel Compatible with Arduino](#) –  
Develop a working robot/car and characterize it under varying scenarios – be creative!
2. Measure and characterize its EMC behavior, possibly consider:
  - Radiated and conducted emissions
  - Power-supply ripple or noise
  - Susceptibility or immunity to defined disturbances (ESD, ripple injection, nearby RF source)
3. Develop a concise measurement plan, use accessible tools (e.g., SDR, LISN substitute, current probe, log detector), and present quantitative results.
4. Summarize findings, identify major coupling paths or emission sources, and — optionally — implement one verified mitigation (e.g., layout, filter, shielding, or firmware change).



**[www.2026.emcsipi.org](http://www.2026.emcsipi.org)**

#IEEE\_ESP26



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SOCIETY®**

## ELIGIBILITY

- Teams of 2-5 students currently enrolled in undergraduate or graduate or PhD programs.
- Each team must have one faculty or industry mentor (IEEE member encouraged but not required).
- Work must be primarily student-led.
- Each university or organization may submit up to two teams.

## AWARDS

Top teams will receive:

**1st Place: \$2000 + certificate**

**2nd Place: \$1000 + certificate**

**3rd Place: \$500 + certificate**

All finalist teams will be invited to demonstrate their projects at the IEEE EMC+SIPI Symposium.

## KEY DATES AND DELIVERABLES

### FEBRUARY 13, 2026

Team Registration and Initial Abstract ( $\leq 1$  page)

### APRIL 30, 2026

Preliminary Report ( $\leq 3$  pages) - test plan, setup photos, early data

### JUNE 30, 2026

Final Submission - Technical report ( $\leq 5$  pages) describing objectives, setup, measurements, data, and conclusions and a 3-minute video showing the device, measurement process, and key results

### AUGUST 2026

Live Demonstrations & Judging at IEEE EMC+SIPI Symposium (Poster or PPT presentation, remote/hybrid)

### DURING SYMPOSIUM

Winners Announced at Awards Luncheon



## JUDGING CRITERIA (equal weighting)

**Measurement Rigor:** Clarity, calibration, and repeatability of the test setup.

**Data Quality & Interpretation:** Completeness of emissions/immunity coverage and meaningful analysis.

**Creativity & Innovation:** Ingenuity in methods, fixtures, or mitigation solutions.

**Educational Value:** Clear communication, reproducibility, and insight for other students.

**Documentation:** Quality of written report and video presentation.

**ALL FINALIST TEAMS WILL BE INVITED TO DEMONSTRATE THEIR PROJECTS AT THE IEEE EMC+SIPI SYMPOSIUM**

## SUBMISSION INSTRUCTIONS

All materials must be submitted electronically by completing the application form at [2026.emcsipi.org/programs/student-hardware-competition](https://2026.emcsipi.org/programs/student-hardware-competition).

## CONTACT

Questions may be directed to the EMC Society Student Hardware Design Competition Chair:  
Prof. Chuck Bunting, Ph.D., F.IEEE at [reverb@okstate.edu](mailto:reverb@okstate.edu)